



LUXELL CORE-S

Low-cost linear uncooled MWIR readout module with USB output Optimal system for low cost solutions

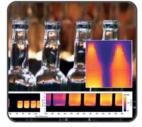
- ▶ Electronic plug-and-play readout module based in microcontroller ARM M3 CORTEX architecture for linear LUXELL FPA (64, 128 & 256 px)
- ▶ LUXELL FPA included with the module
- ▶ Band of detection: MWIR (1 5 microns)
- ▶ Peak wavelength of detection: 3.7 microns
- ▶ Readout (A/D) channels: 2
- Integration time: 4 20 μs, selectable
- ▶ Maximum scanning rate (@ minimum integration time):
 - ▶ 1200 lines per sec (64 px)
 - ▶ 600 lines per second (128 px)
 - ▶ 300 lines per second (256 px)
- Intelligent dark current substraction on-board
- ▶ Start-up time: < 5 seconds
- ▶ Communication interface: USB 2.0 full speed
- Data transmission: raw data, 14 bits
- ▶ Power: 1W (USB powerer, 5 VDC, 200 mA)
- ▶ Minimum temperature of detection: 100 °C
- ▶ Dimensions of the OEM electronic module (in mm): 56 (L) x 40 (W) x 40 (H)
- ▶ Weight of the OEM module (grams): 60 g
- ▶ Metal housing available, with M35x1 optics interface, rear connectors, and tripod screw [housing dimensions, in mm: 80 (L) x 45 (W) x 50 (H)]
- ▶ Front plate with lens holder: available
- ▶ Optics available (M35x1 interface):
 - ▶ 64 px: f=9 mm, f=24 mm, f=48 mm
 - ▶ 128 px & 256 px: f=35 mm, f=70 mm
- ▶ Software included: NIT SOFTWARE SUITE (Acquisition and visualization SW)
- ▶ LabVIEW SDK for custom software programming available
- ▶ Industrial applications: industrial welding process monitoring, laser processing, glass manufacturing quality assurance, machine vision



(welding, cutting, etc)



Steel manufacturing industry Process Quality Assurance

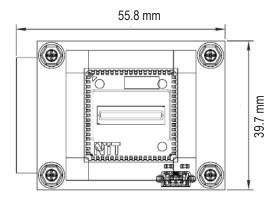


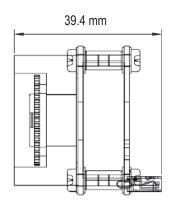
Glass manufacturing quality assurance



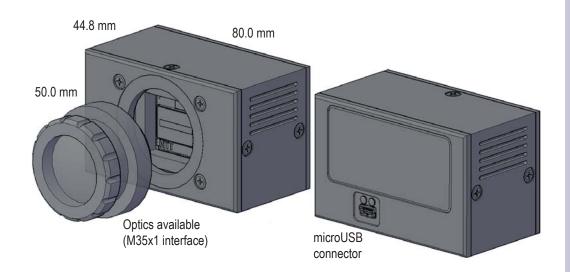


LUXELL CORE-S module





LUXELL CORE-S with external housing and lens



LUXELL FPA



- ▶ FPA resolution: 64, 128, 256 pixels
- Uncooled operation
- ▶ Band of detection: MWIR (1 5 um)
- ▶ Peak detection wavelength: 3.7 um
- ▶ D* (WLpeak) (typ): 2x10⁹ Jones
- ▶ Response time: 2 us
- Pixel size:
 - ▶ 64 px, 128 px: 100x1000 um²
 - > 256 px: 60x600 um²
- Pixel pitch:
 - ▶ 64 px, 128 px: 100 um
 - > 256 px: 60 um

- ▶ Readout method: x-y multiplexed
- Readout electronics: not included (CORE-S compatible)
- ▶ Packaging: SMD / LCC68 footprint
- Dimensions (mm): 24x24x2.2
- Biasing voltage (typ): 5 V
- Pixel resistance (typ): 0.2 1.0 MOhm

Typical applications

- Industrial manufacturing process control (welding, cutting, etc.)
- Laser process monitoring
- Gas and flame detection
- Machine vision
- OEM integration

Industries of use

- Automotive industry
- Home appliance manufacturing
- Metallurgy and steel industry
- Petrochemical industry

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